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(12) **United States Design Patent**
Lee et al.
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(45) **Date of Patent: ** Aug. 2, 2016**

(54) **LIGHT EMITTING DIODE PACKAGE SUBSTRATE**

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(73) Assignee: **Genesis Photonics Inc.**, Tainan (TW)

(**) Term: **14 Years**

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(22) Filed: **Apr. 2, 2015**

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
USPC D13/180; D26/1
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15; H01L 27/156; H01L 31/02; H01L 33/00; H01L 33/04; H01L 33/08; H01L 33/10; H01L 33/20; H01L 33/38; H01L 33/42; H01L 33/62; H01L 33/483; H01L 33/486; F21K 9/00; F21K 9/30; F21K 9/54
See application file for complete search history.

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Primary Examiner — Selina Sikder
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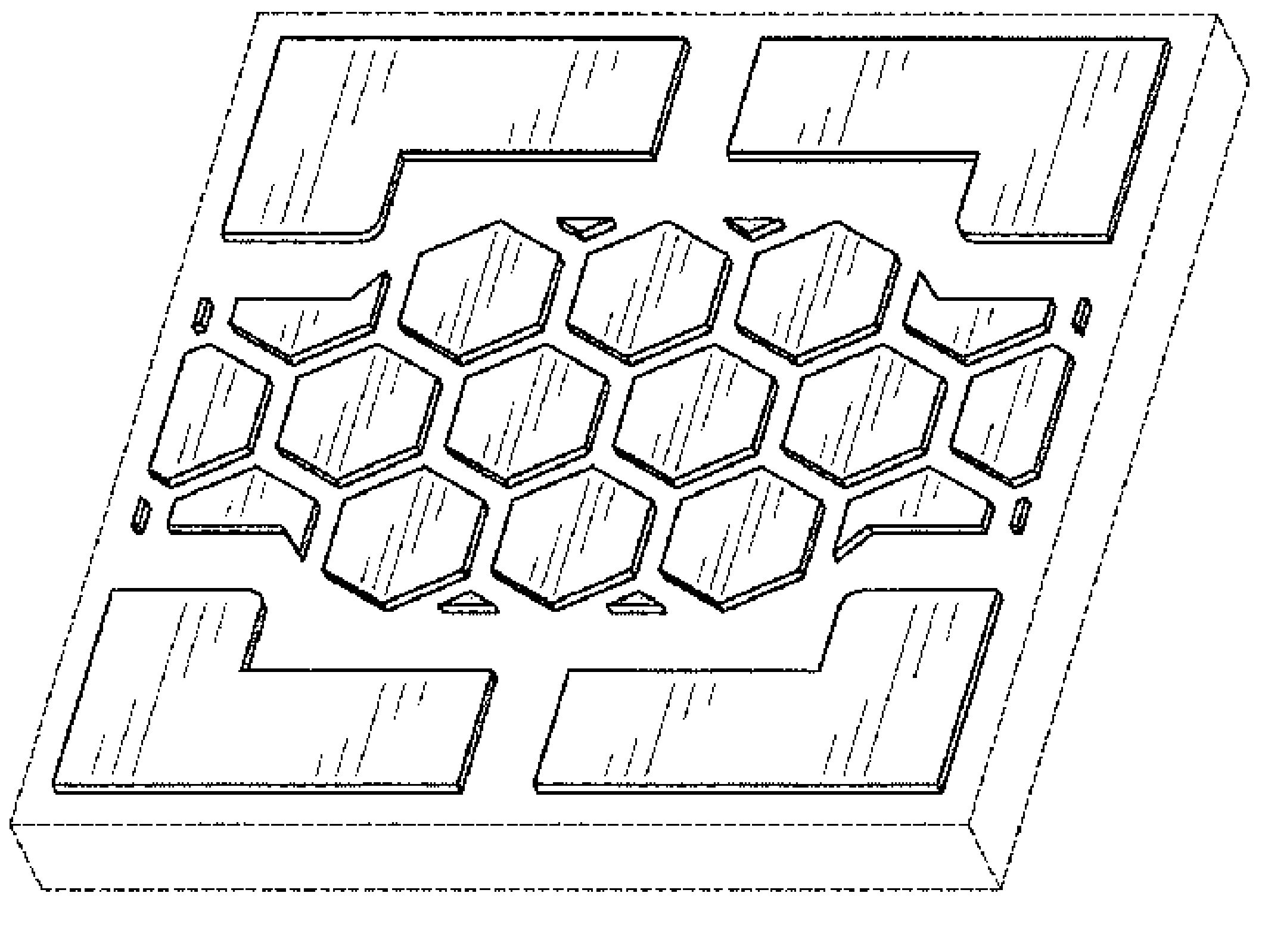
(57) **CLAIM**

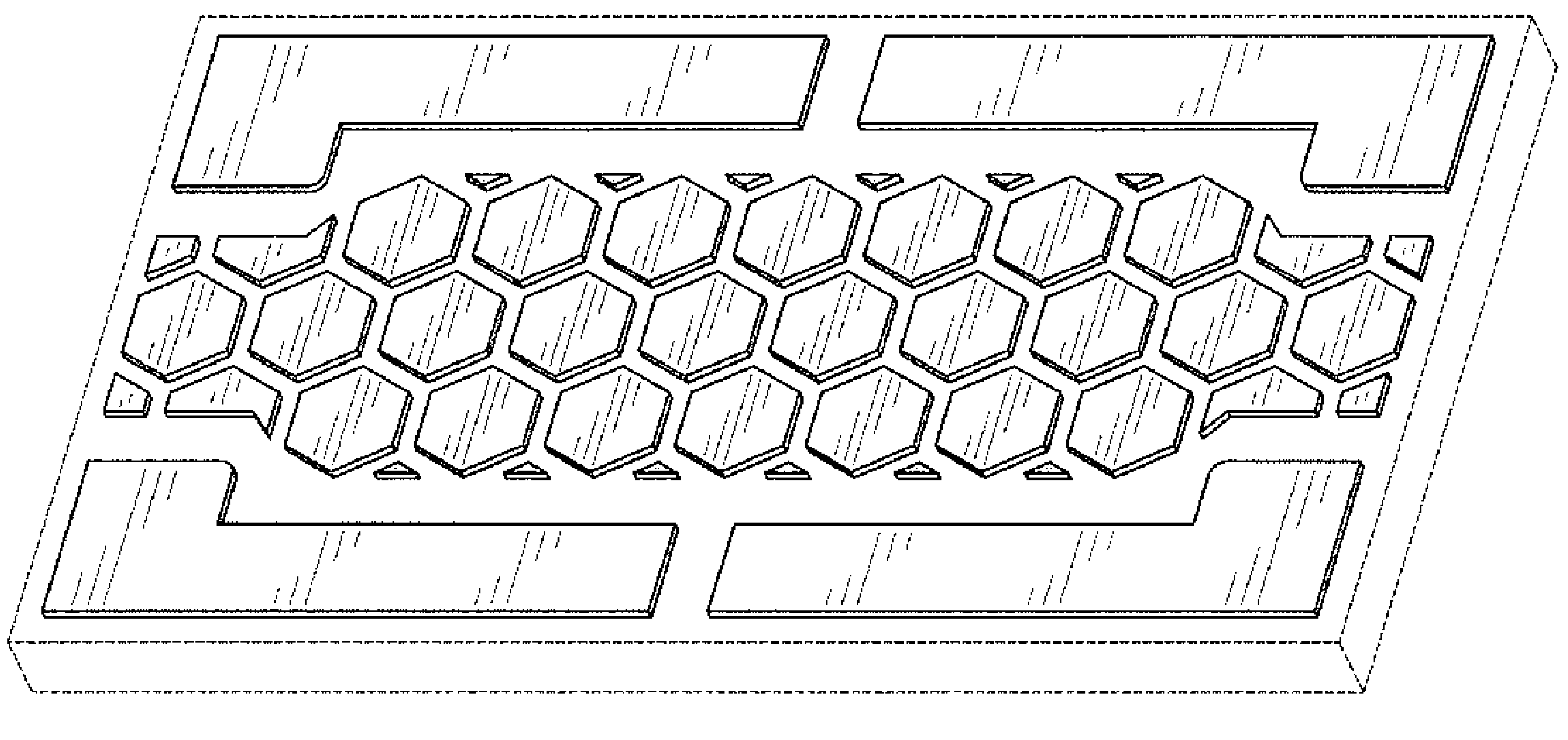
The ornamental design for a light emitting diode package substrate, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a first embodiment of a light emitting diode package substrate showing our new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is top view thereof;
FIG. **7** is a bottom view thereof;
FIG. **8** is a perspective view thereof with a light emitting diode chip mounted;
FIG. **9** is a perspective view of a second embodiment thereof;
FIG. **10** is a front view thereof;
FIG. **11** is a rear view thereof;
FIG. **12** is a left side view thereof;
FIG. **13** is a right side view thereof;
FIG. **14** is top view thereof;
FIG. **15** is a bottom view thereof;
FIG. **16** is a perspective view thereof with light emitting diode chips mounted;
FIG. **17** is a perspective view of a third embodiment thereof;
FIG. **18** is a front view thereof;
FIG. **19** is a rear view thereof;
FIG. **20** is a left side view thereof;
FIG. **21** is a right side view thereof;
FIG. **22** is top view thereof;
FIG. **23** is a bottom view thereof; and,
FIG. **24** is a perspective view thereof with light emitting diode chips mounted.
The broken lines are for the purpose of illustrating portions of the light emitting diode package substrate and the light emitting diode chips and form no part of the claimed design. The light shade lines on the surface portions indicate contour and not surface decoration.

1 Claim, 12 Drawing Sheets





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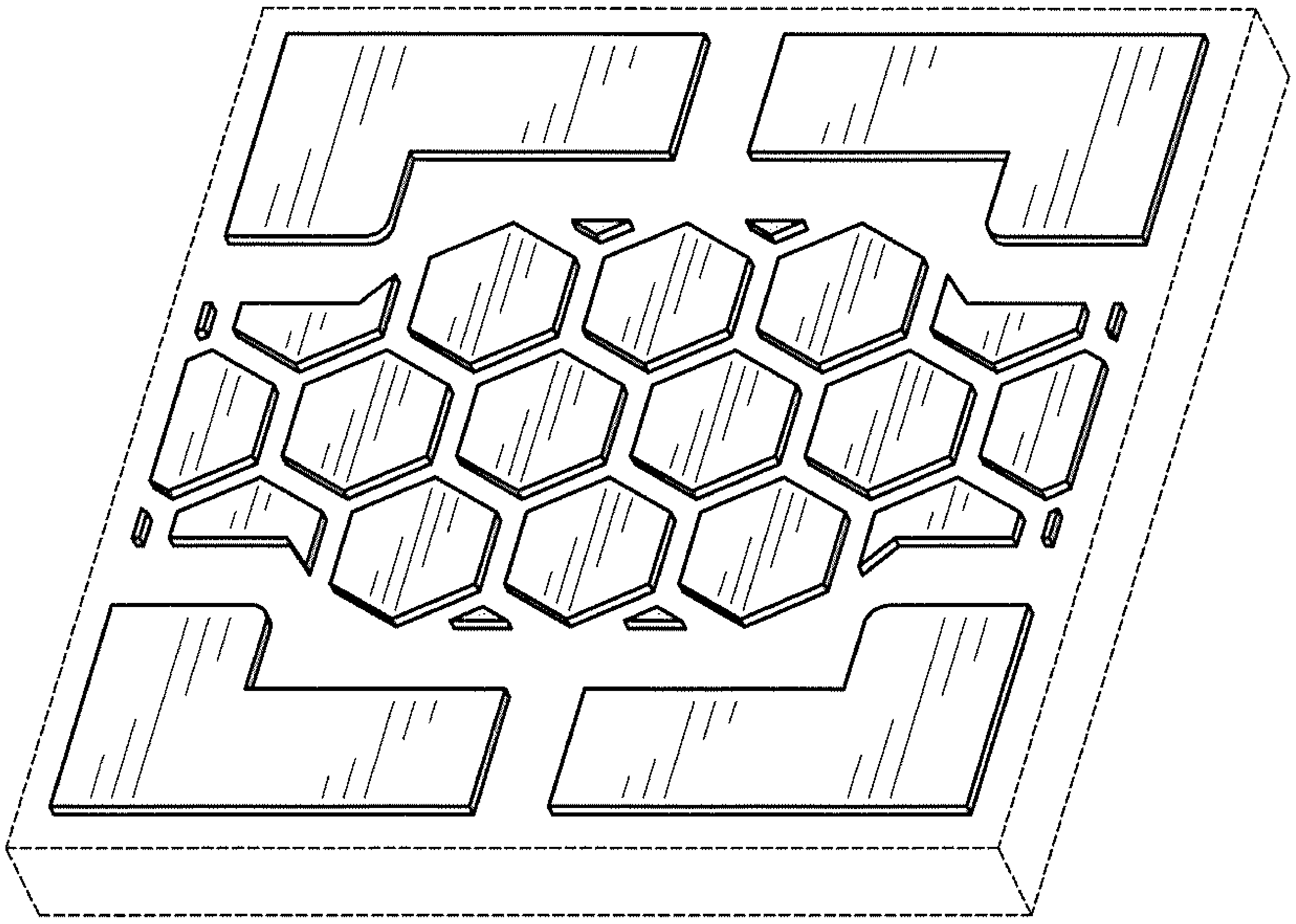

FIG. 1

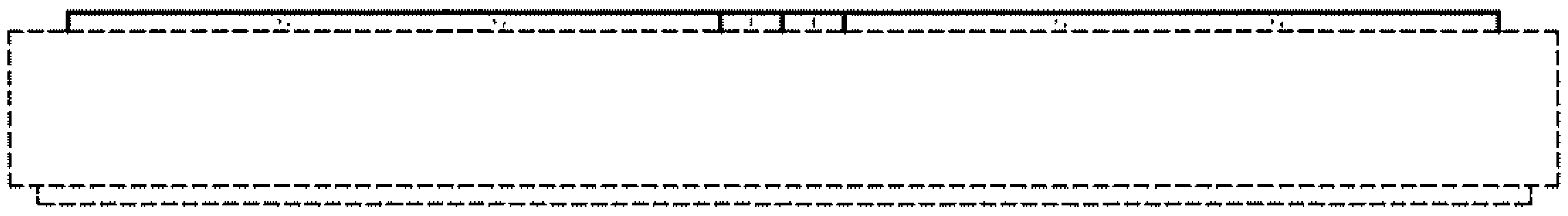

FIG. 2

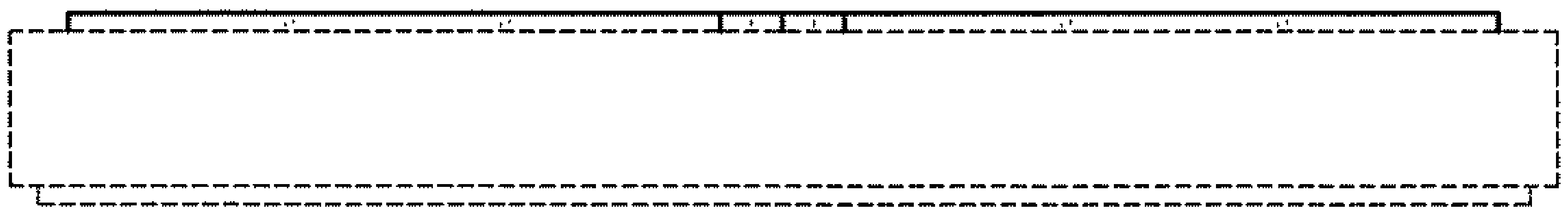

FIG. 3

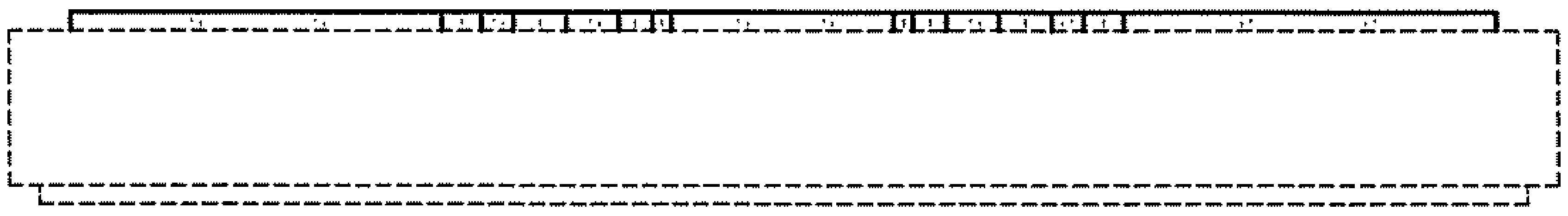

FIG. 4

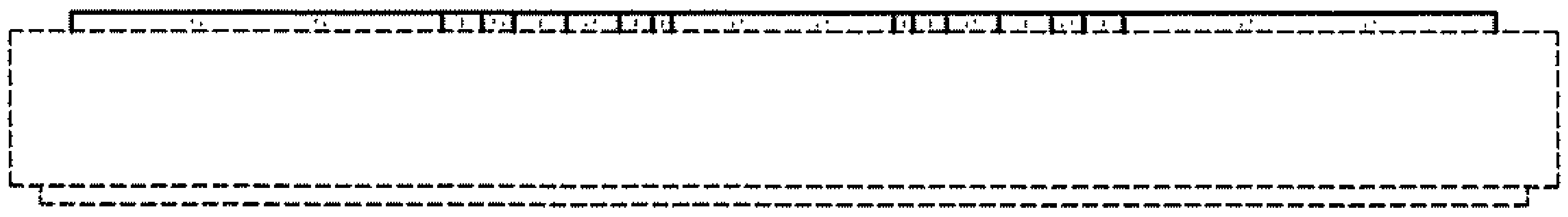

FIG. 5

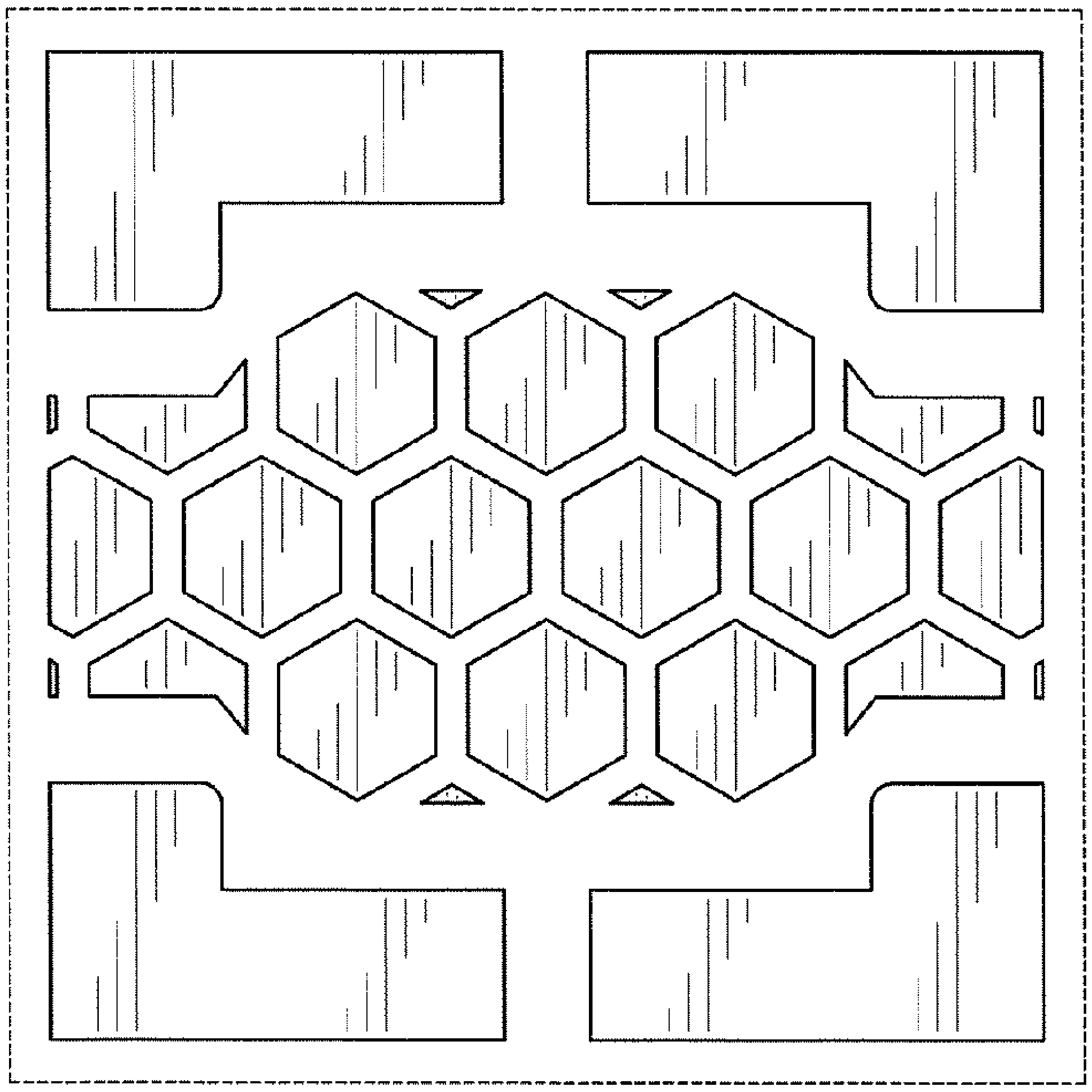

FIG. 6

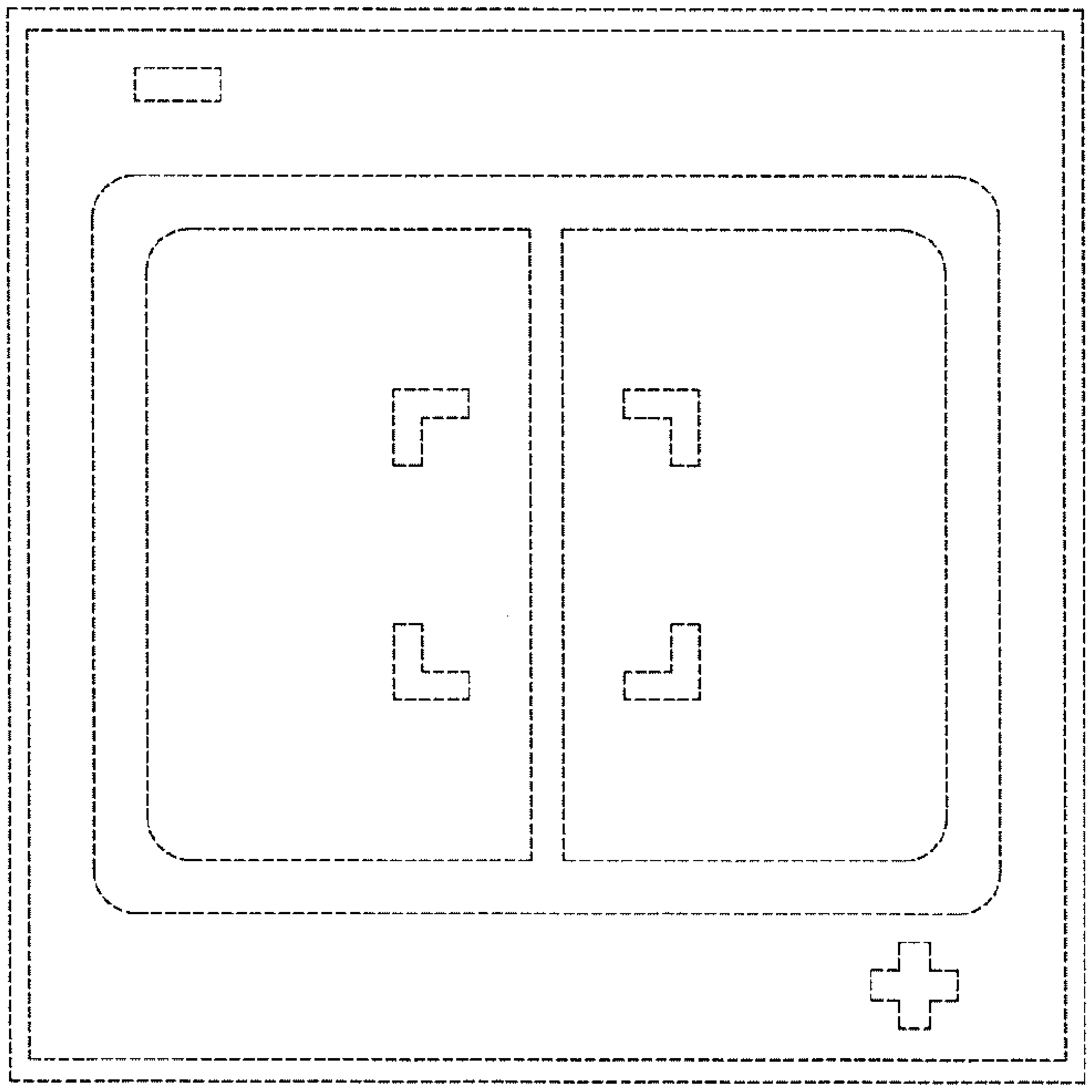

FIG. 7

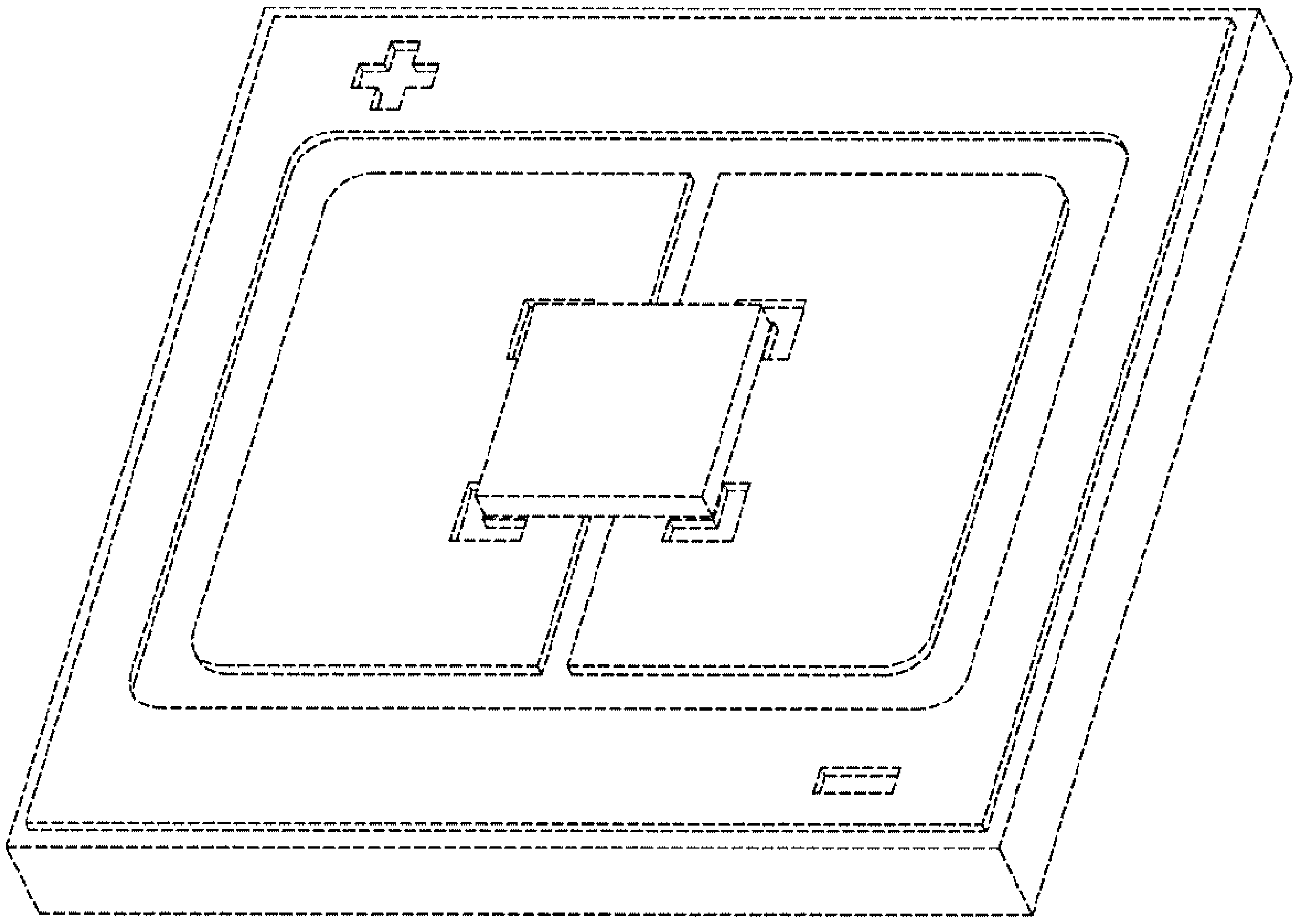

FIG. 8

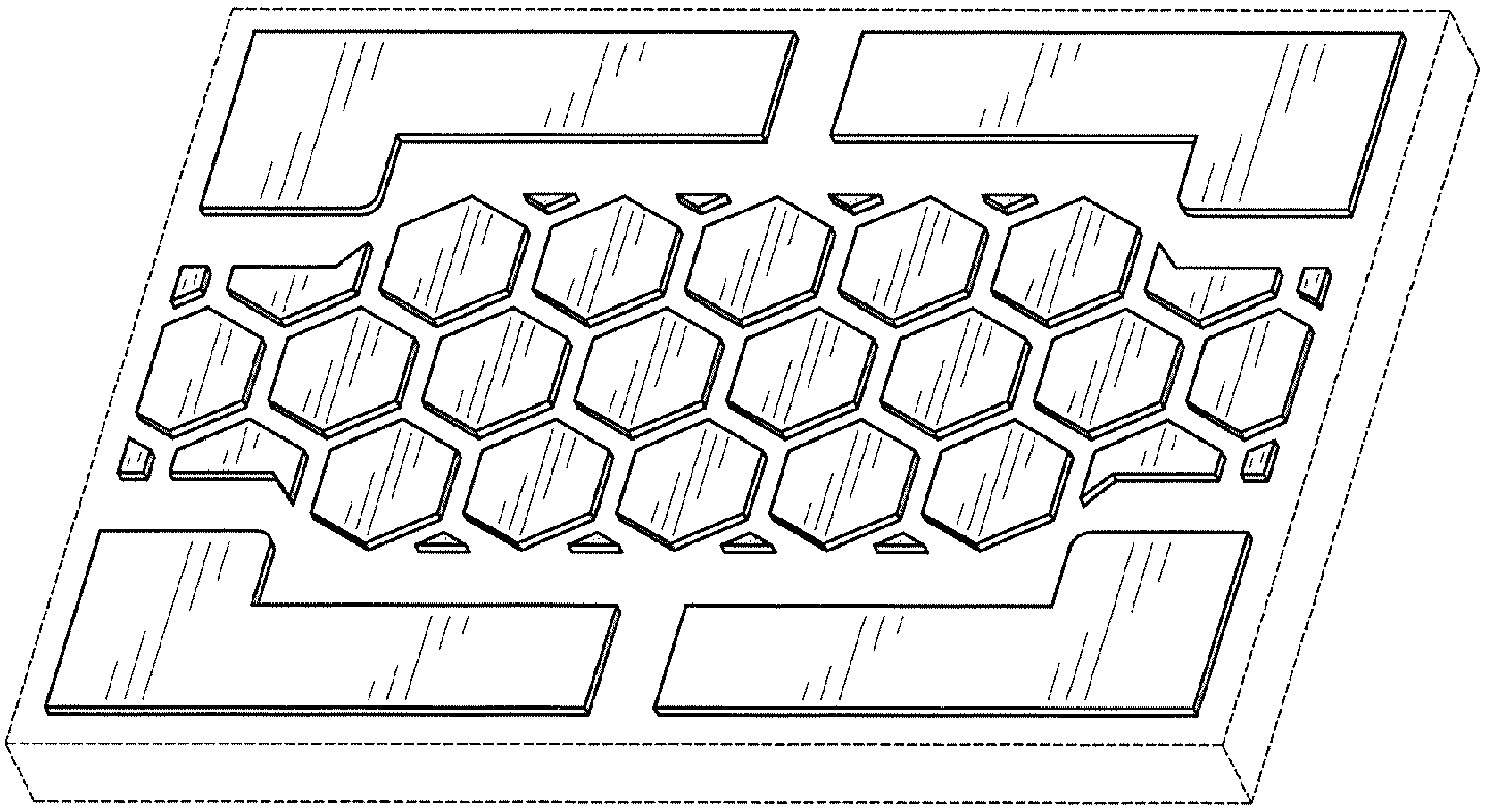

FIG. 9

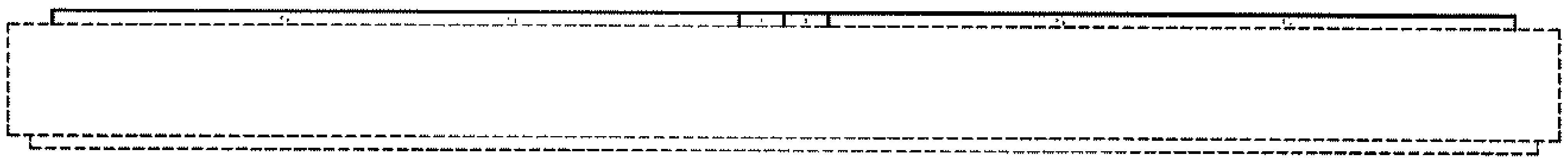

FIG. 10

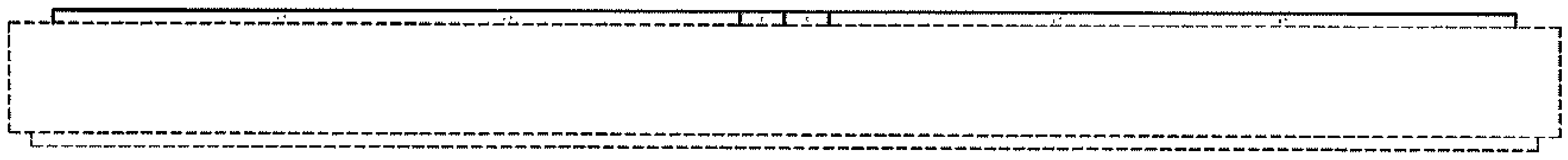

FIG. 11

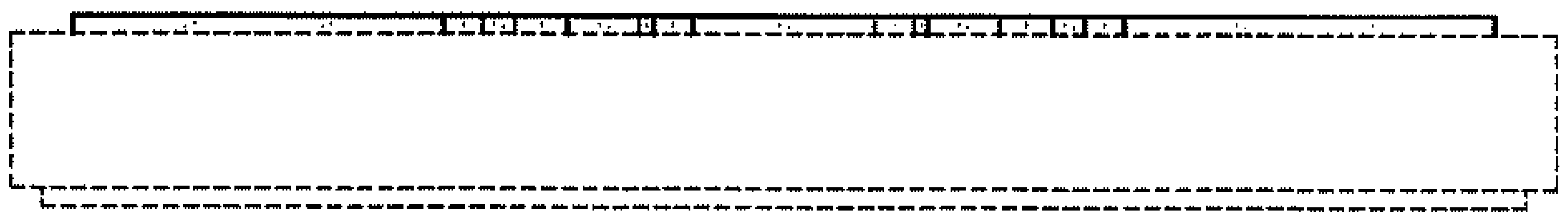

FIG. 12

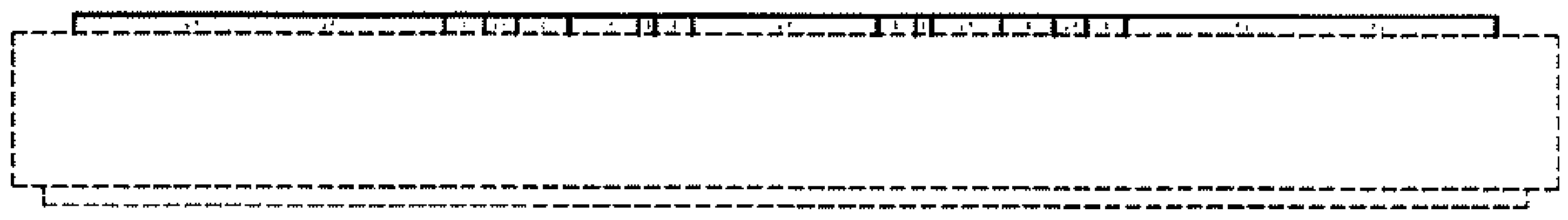

FIG. 13

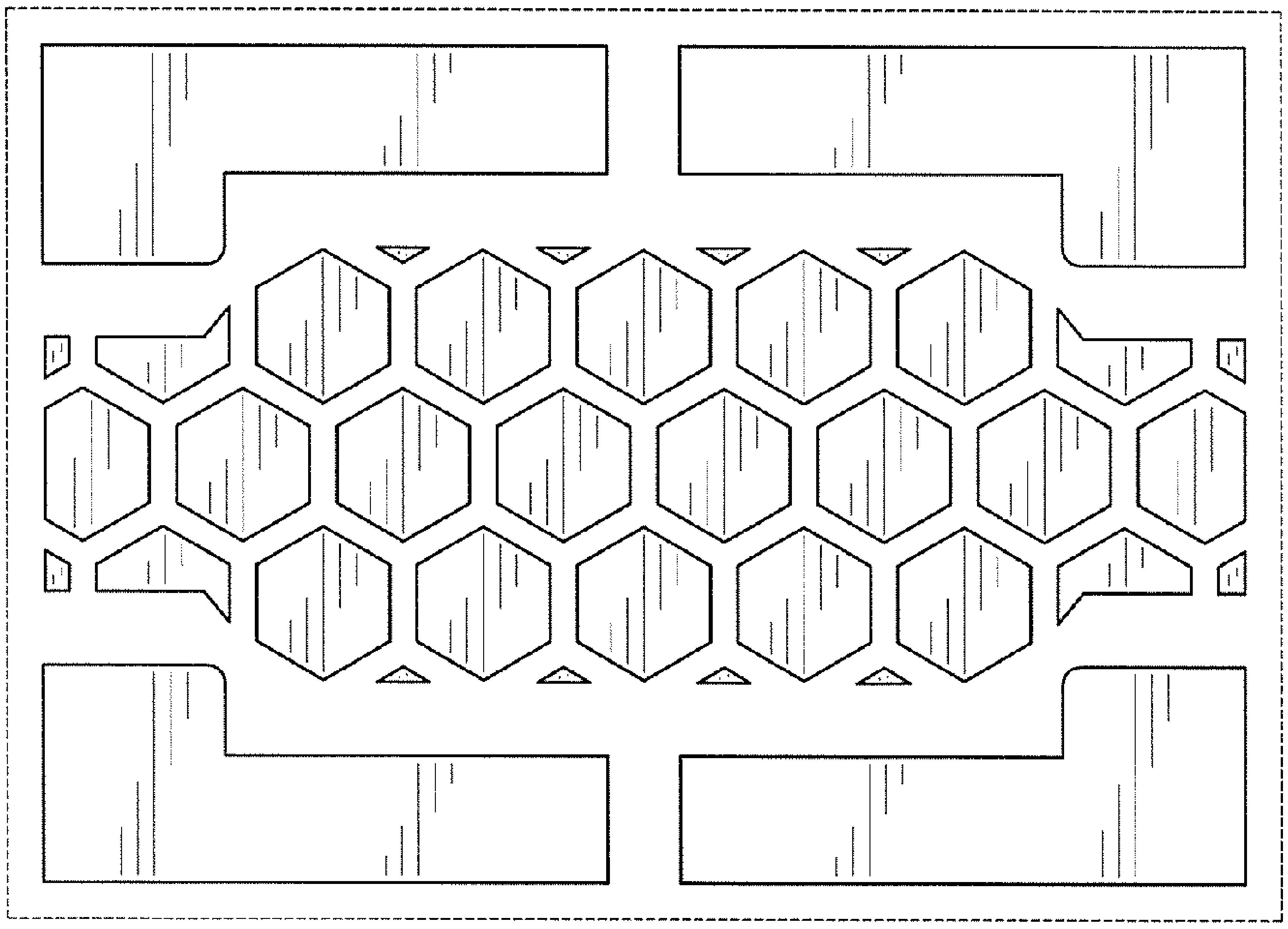

FIG. 14

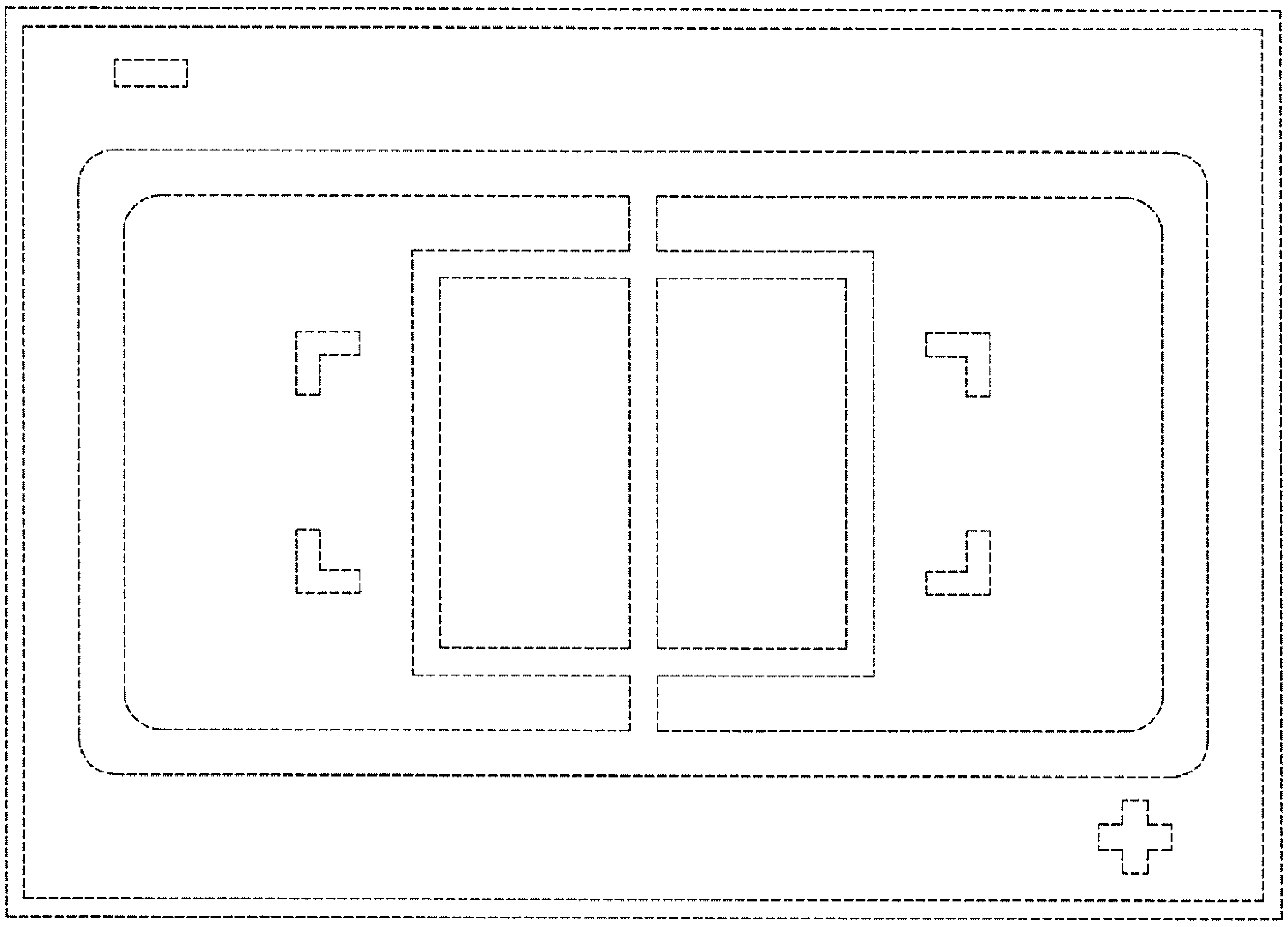

FIG. 15

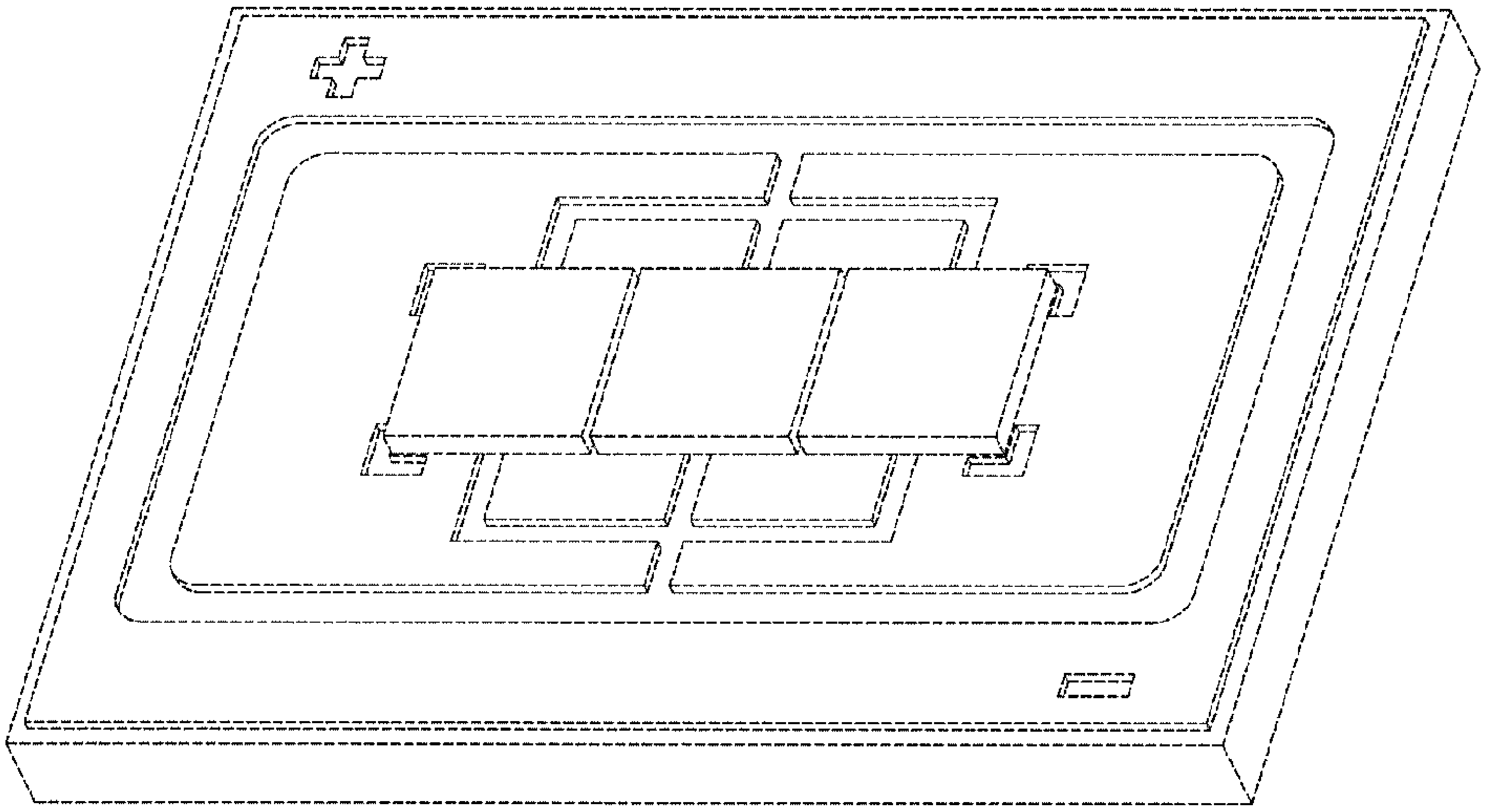

FIG. 16

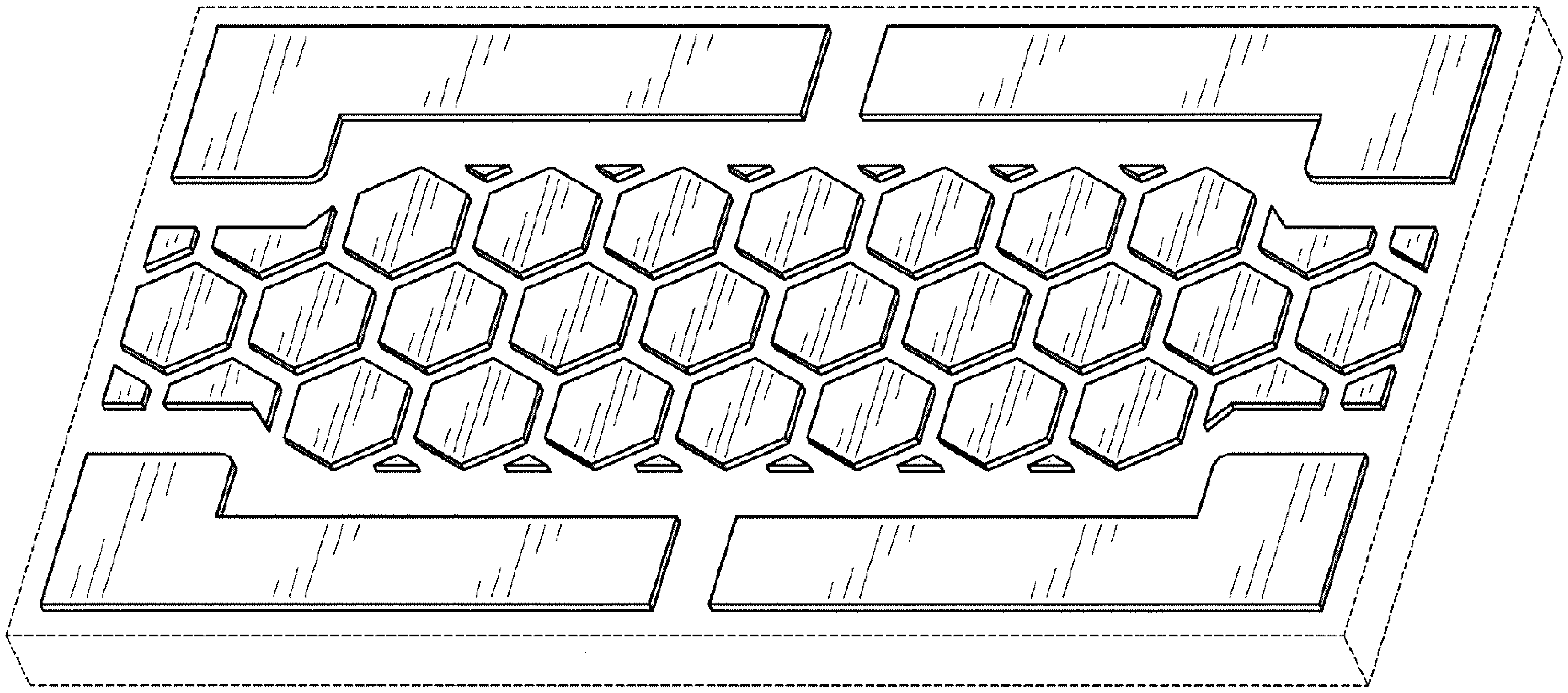

FIG. 17

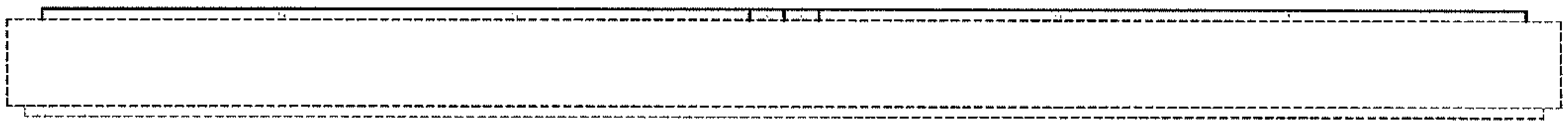

FIG. 18

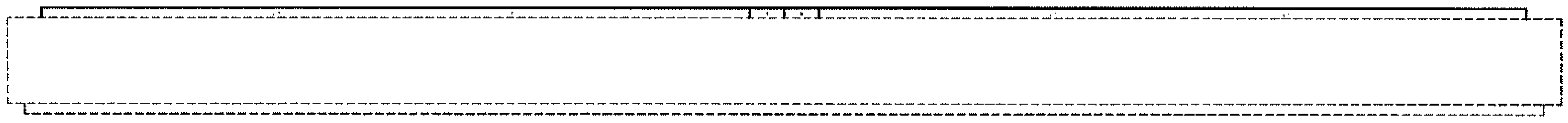

FIG. 19

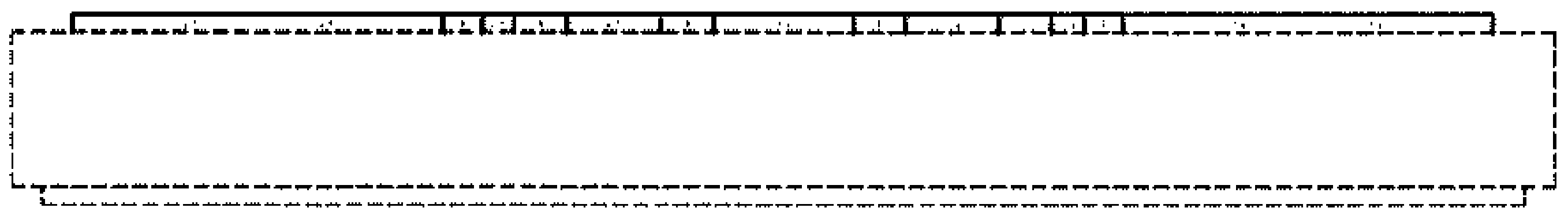

FIG. 20

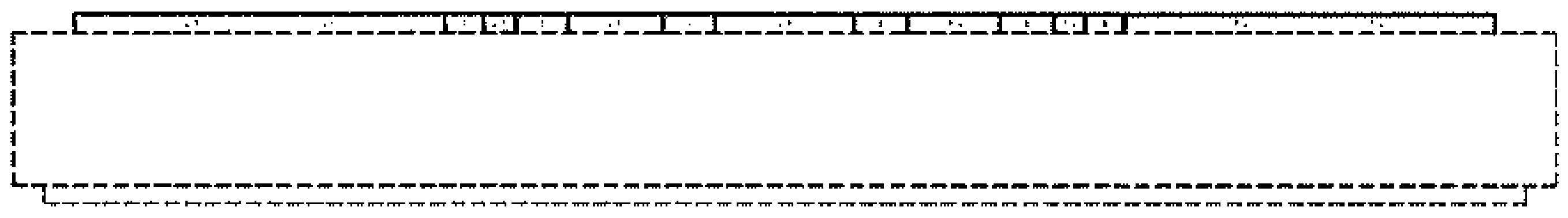

FIG. 21

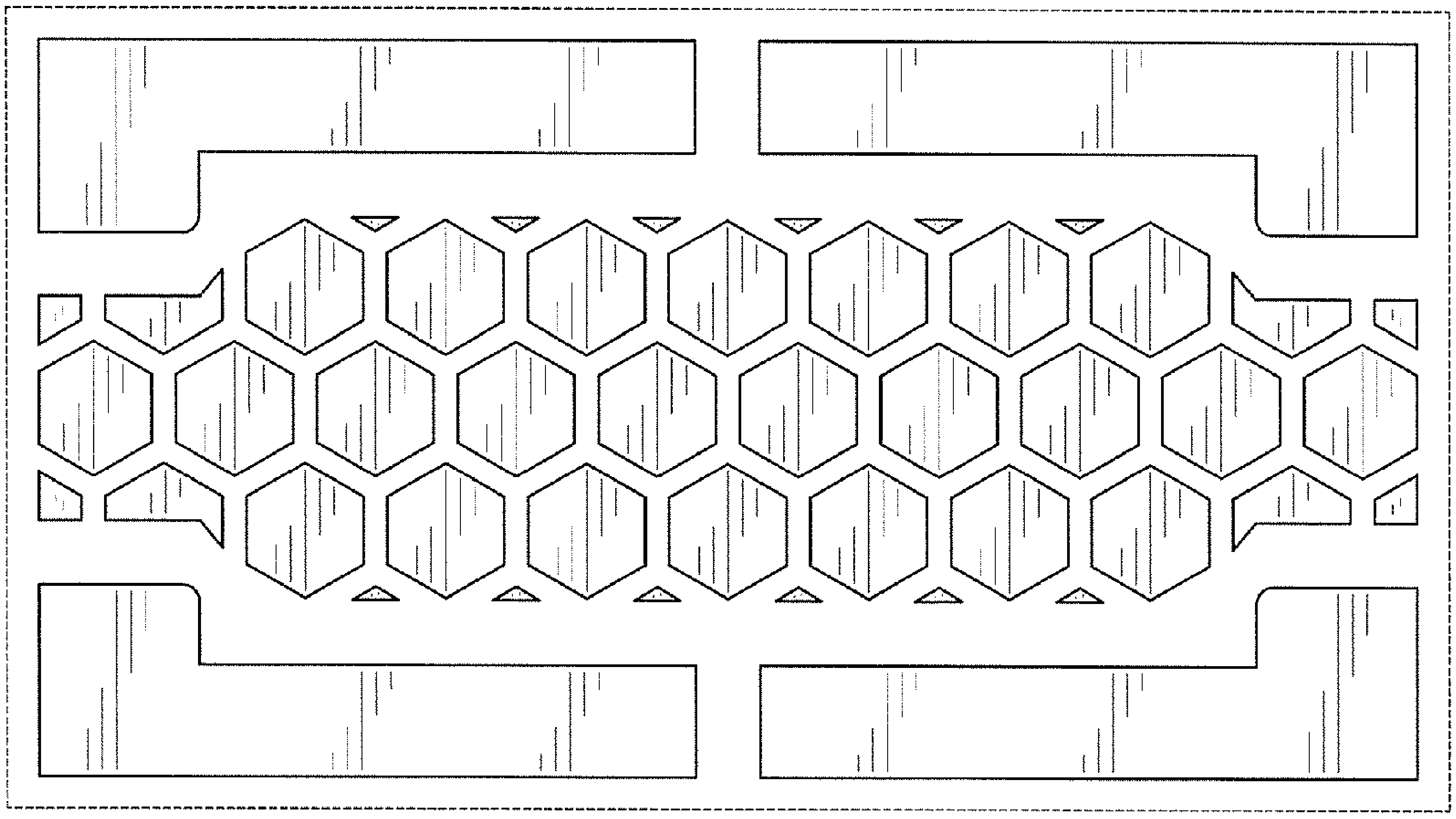

FIG. 22

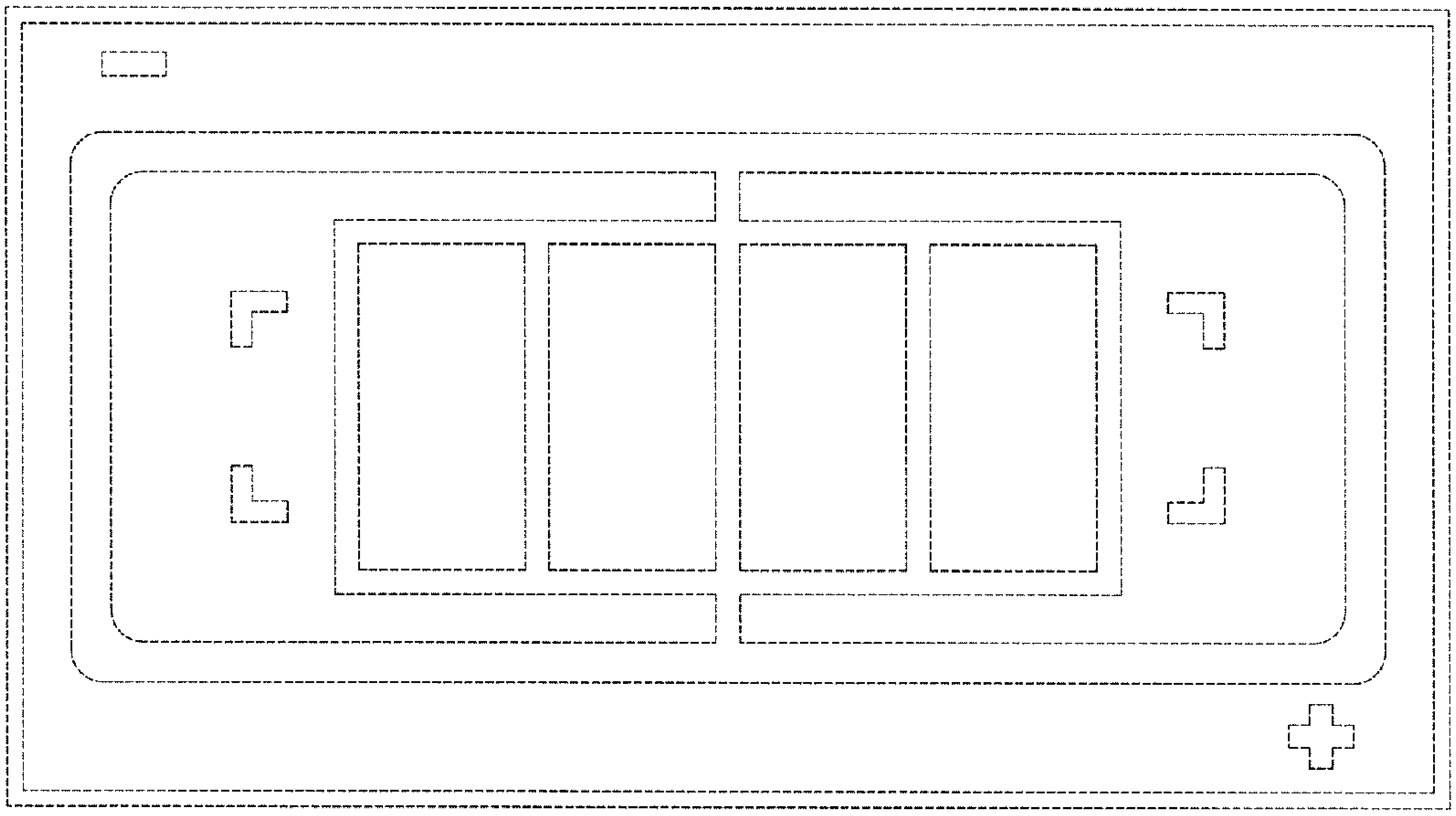

FIG. 23

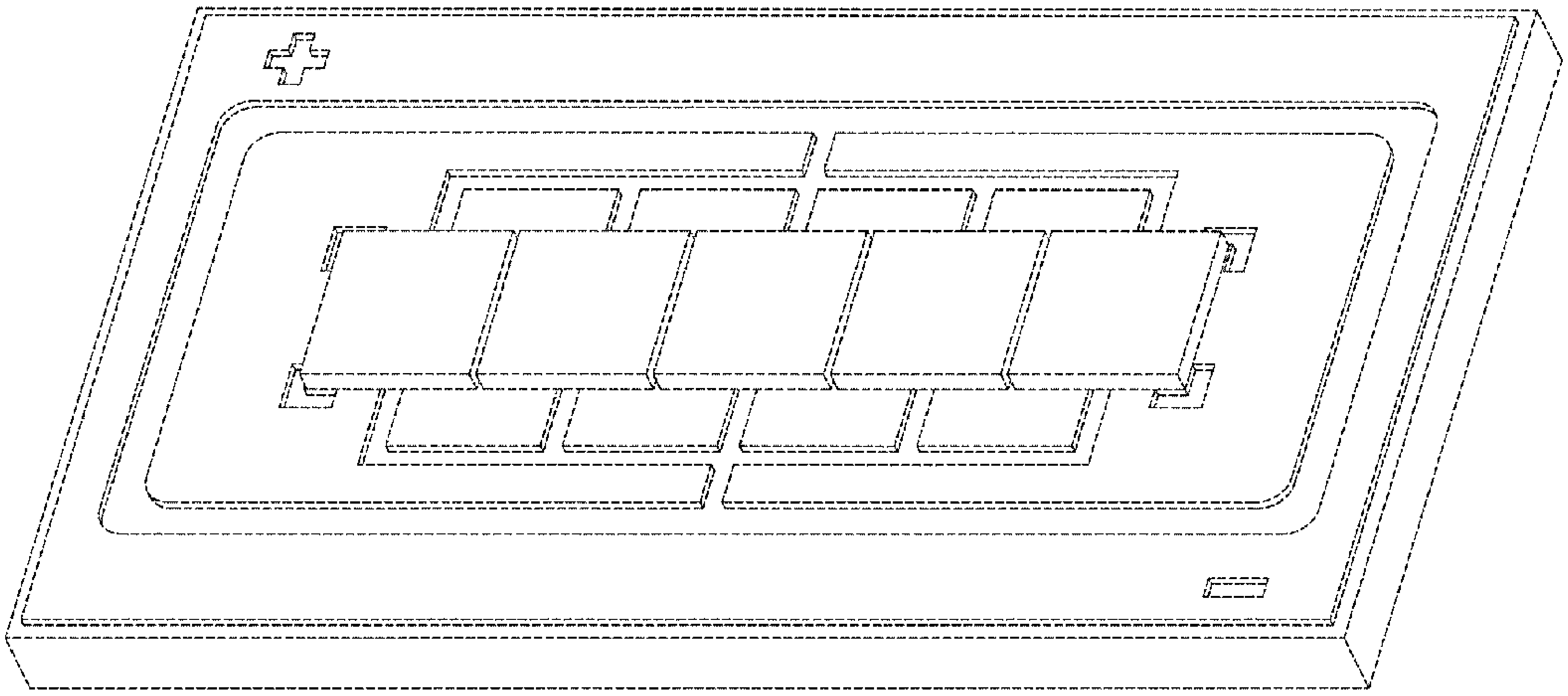

FIG. 24